

Schottky Barrier Diode NSR0170

Schottky barrier diodes are optimized for very low forward voltage drop and low leakage current making them ideal devices to be used in a wide range of dc-dc converter, clamping and protection applications. NSR0170 in SOD-323, SOD-923 and X2DFNW2 miniature packages enable designers to meet the challenging task of achieving higher efficiency while meeting reduced PCB space requirements.

Features

- Very Low Forward Voltage Drop 560 mV @ 10 mA
- Low Reverse Current 25 nA @ 50 V VR
- 70 mA of Continuous Forward Current
- Power Dissipation of 240 mW with Minimum Trace
- Very High Switching Speed
- Low Capacitance CT = 2 pF
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- NSVR0170MX2WT5G Wettable Flank Package for Optimal Automated Optical Inspection (AOI)
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- LCD and Keypad Backlighting
- · Camera Photo Flash
- Buck and Boost DC-DC Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

Markets

- Mobile Handsets and MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS
- Automotive ECUs

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V_{R}	70	V
Forward Current (DC)	lF	70 n	
ESD Rating: Human Body Model Machine Model	ESD	Class Class	_

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

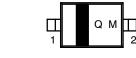
70 V SCHOTTKY BARRIER DIODE



MARKING DIAGRAMS



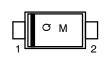
CASE 477



Q = Specific Device Code M = Month Code



CASE 514AB



Q = Specific Device Code M = Month Code





Q = Specific Device Code M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
NSR0170HT1G	SOD-323 (Pb-Free)	3000/
NSVR0170HT1G	(PD-Free)	Tape & Reel
NSR0170P2T5G	SOD-923 (Pb-Free)	2 mm Pitch 8000/
NSVR0170P2T5G	(Fb-Fiee)	Tape & Reel
NSVR0170MX2WT5G	X2DFNW2 (Pb-Free)	8000/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NSR0170

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			520 240	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			175 710	°C/W mW
Junction and Storage Temperature Range	T _J , T _{stg}			-55 to +150	°C

- Mounted onto a 4 in square FR-4 board 10 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
 Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V _R = 50 V) (V _R = 70 V)	I _R		25 -	90 3.0	nΑ μΑ
Forward Voltage (I _F = 1.0 mA) (I _F = 10 mA) (I _F = 15 mA)	V _F		0.34 0.56 0.65	0.39 0.64 0.73	V
Total Capacitance (V _R = 0 V, f = 1 MHz)	СТ		2.0		pF

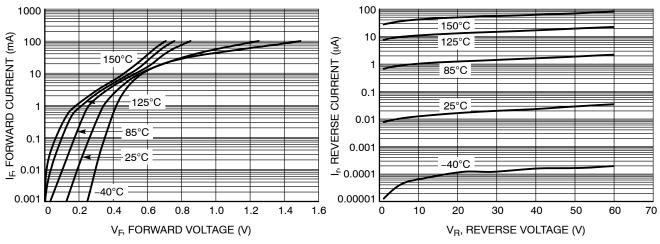


Figure 1. Forward Voltage

Figure 2. Leakage Current

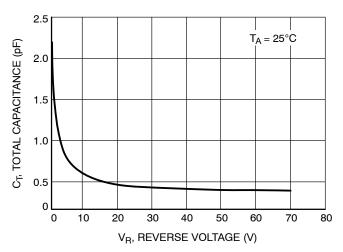


Figure 3. Total Capacitance

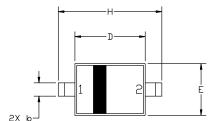






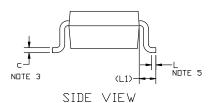
SOD-323 1.70x1.25x0.85 **CASE 477 ISSUE K**

DATE 11 MAR 2024

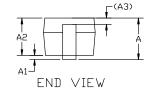


NOTES:

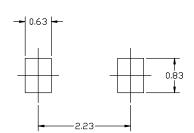
- 1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
- CONTROLLING DIMENSION: MILLIMETERS. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH 3. SOLDER PLATING.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
 DIMENSION L IS MEASURE FROM END OF RADIUS.



TOP VIEW



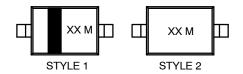
DIM	MI	LLIMETE	RS
ויונע	MIN.	N□M.	MAX.
Α	0.80	0.90	1.00
A1	0.00	0.05	0.10
A2	0.75	0.85	0.95
АЗ	0.15 (REF)		
b	0.25	0.32	0.4
C	0.09	0.12	0.18
D	1.60	1.70	1.80
E	1.15	1.25	1.35
Н	2.30	2.50	2.70
L	0.08		
L1	0.40 (REF)		



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques
Reference manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*



XX = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

STYLE 2: NO POLARITY PIN 1. CATHODE (POLARITY BAND) 2. ANODE

DOCUMENT NUMBER:	98ASB17533C	Electronic versions are uncontrolled except when accessed directly from the Document Repos Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOD-323 1.70x1.25x0.85		PAGE 1 OF 1

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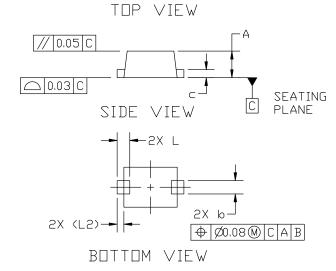
SOD-923 0.80x0.60x0.37 CASE 514AB ISSUE E

DATE 08 FEB 2024

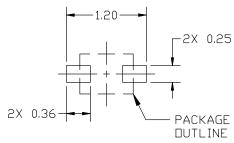


В

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
- 5. DIMENSION L WILL NOT EXCEED 0.30mm.



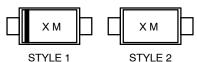
\ 	MILLIM	IETERS	2
DIM	MIN.	N□M.	MAX.
А	0.34	0.37	0.40
b	0.15	0,20	0,25
C	0.07	0.12	0.17
D	0.75	0.80	0,85
E	0.55	0,60	0,65
Н	0.95	1.00	1.05
Ĺ		0.19 REF	•
L2	0.05	0.10	0.15



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1: STYLE 2: NO POLARITY BAND) NO POLARITY 2. ANODE

DOCUMENT NUMBER:	98AON23284D	Electronic versions are uncontrolled except when accessed directly from the Document Rep Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION	SOD-923 0.80x0.60x0.37		PAGE 1 OF 1

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 $2X \triangle 0.05 C$

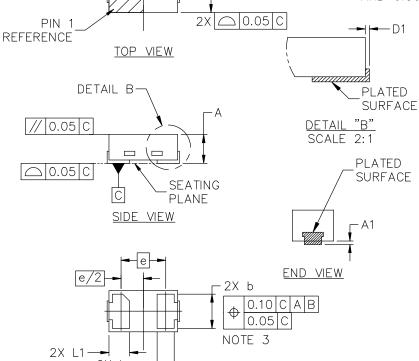
D

X2DFNW2 1.00x0.60x0.37, 0.65P CASE 711BG ISSUE D

DATE 29 FEB 2024



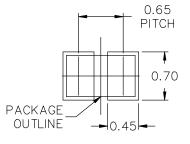
- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
 - 2. ALL DIMENSION ARE IN MILLIMETERS.
- DIMENSION 6 APPLIES TO THE PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 FROM THE TERMINAL TIP.



В

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DIM	MILLIMETERS			
ואווט	MIN.	NOM.	MAX.	
А	0.34	0.37	0.40	
A1			0.05	
b	0.45	0.50	0.55	
D	1.00 BSC			
D1			0.05	
Е	0.60 BSC			
е	0.65 BSC			
L	0.22 REF			
L1	0.24	0.28	0.34	



RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

BOTTOM VIEW



XX = Specific Device Code M = Date Code

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DESCRIPTION:	X2DFNW2 1.00x0.60x0.37, 0.65P		PAGE 1 OF 1

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